



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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企业微信二维码



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Features

- $BV_{CEO} > 40V$
- Epitaxial Planar Die Construction
- Ideally Suited for Automated Assembly Processes
- Complementary PNP Type Available: DIODES™ NK-DZT2907A

Mechanical Data

- Package: SOT223
- Package Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.112 grams (Approximate)

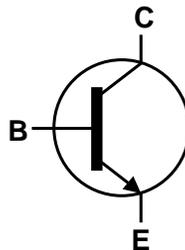
Applications

- Medium power switching & amplification

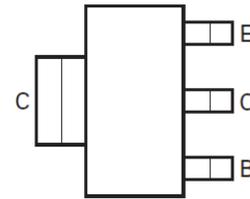
SOT223



Top View



Device Symbol



Top View
Pin-Out

Absolute Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CB0}	75	V
Collector-Emitter Voltage	V_{CEO}	40	V
Emitter-Base Voltage	V_{EBO}	6	V
Collector Current	I_C	600	mA

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_D	0.83	W
Thermal Resistance, Junction to Ambient Air (Note 5)	$R_{\theta JA}$	150	$^\circ\text{C/W}$
Thermal Resistance, Junction to Case (Note 5)	$R_{\theta JC}$	53	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Note: 5. For a device mounted on minimum recommended pad (MRP) layout that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.

Thermal Characteristics and Derating Information

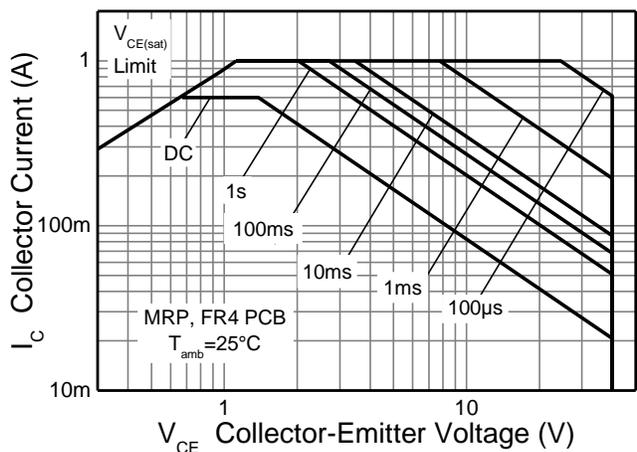


Figure 1. Safe Operating Area

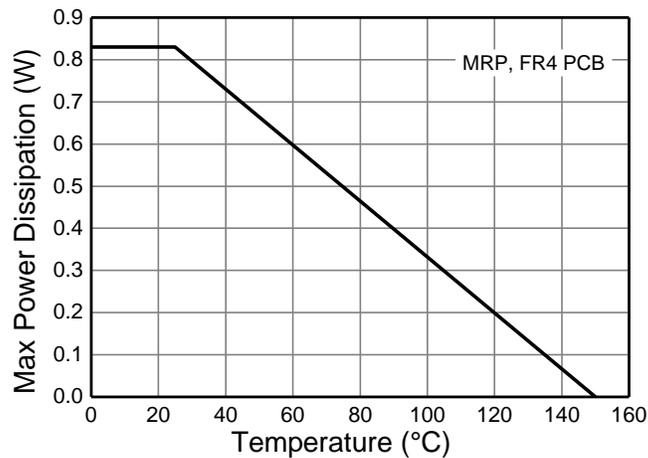


Figure 2. Derating Curve

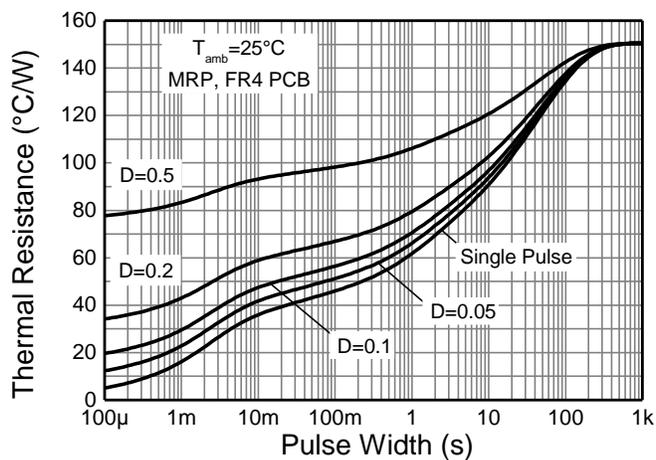


Figure 3 Transient Thermal Impedance

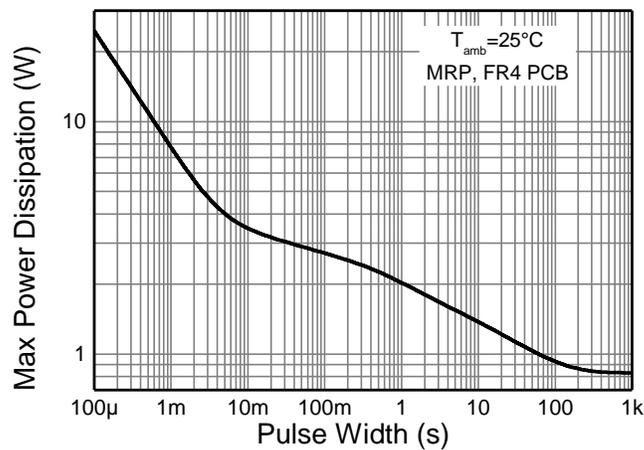


Figure 4 Pulse Power Dissipation

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
OFF CHARACTERISTICS (Note 6)						
Collector-Base Breakdown Voltage	BV_{CBO}	75	125	—	V	$I_C = 100\mu\text{A}$
Collector-Emitter Breakdown Voltage	BV_{CEO}	40	59	—	V	$I_C = 10\text{mA}$
Emitter-Base Breakdown Voltage	BV_{EBO}	6	7.5	—	V	$I_E = 100\mu\text{A}$
Collector-Base Cut-Off Current	I_{CBO}	—	2	10	nA	$V_{CB} = 50\text{V}$
		—	—	10	μA	$V_{CB} = 50\text{V}, T_A = +150^\circ\text{C}$
Emitter-Base Cut-Off Current	I_{EBO}	—	2	10	nA	$V_{EB} = 3\text{V}$
Collector-Emitter Cut-Off Current	I_{CEX}	—	—	10	nA	$V_{CE} = 60\text{V}, V_{EB(off)} = 3\text{V}$
ON CHARACTERISTICS (Note 6)						
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	—	0.11	0.3	V	$I_C = 150\text{mA}, I_B = 15\text{mA}$
		—	0.31	1.0	V	$I_C = 500\text{mA}, I_B = 50\text{mA}$
Base-Emitter Saturation Voltage	$V_{BE(sat)}$	0.6	0.87	1.2	V	$I_C = 150\text{mA}, I_B = 15\text{mA}$
		—	1.04	2.0	V	$I_C = 500\text{mA}, I_B = 50\text{mA}$
DC Current Gain	h_{FE}	35	2.12	—	—	$I_C = 0.1\text{mA}, V_{CE} = 10\text{V}$
		50	263	—		$I_C = 1\text{mA}, V_{CE} = 10\text{V}$
		75	223	—		$I_C = 10\text{mA}, V_{CE} = 10\text{V}$
		35	131	—		$I_C = 10\text{mA}, V_{CE} = 10\text{V}, T_A = -55^\circ\text{C}$
		100	229	300		$I_C = 150\text{mA}, V_{CE} = 10\text{V}$
		50	123	—		$I_C = 150\text{mA}, V_{CE} = 1\text{V}$
		40	67	—		$I_C = 500\text{mA}, V_{CE} = 10\text{V}$
SMALL SIGNAL CHARACTERISTICS						
Transition Frequency	f_T	300	—	—	MHz	$I_C = 20\text{mA}, V_{CE} = 20\text{V}, f = 100\text{MHz}$
Output Capacitance	C_{obo}	—	—	8	pF	$V_{CB} = 10\text{V}, f = 1\text{MHz}$
Input Capacitance	C_{ibo}	—	—	25	pF	$V_{EB} = 0.5\text{V}, f = 1\text{MHz}$
SWITCHING CHARACTERISTICS						
Delay Time	t_d	—	3.9	10	ns	$V_{CE} = 30\text{V}, V_{EB(off)} = 0.5\text{V}, I_C = 150\text{mA}, I_{B1} = 15\text{mA}$
Rise Time	t_r	—	6.4	25	ns	
Storage Time	t_s	—	188	225	ns	$V_{CE} = 30\text{V}, I_C = 150\text{mA}, I_{B1} = -I_{B2} = 15\text{mA}$
Fall Time	t_f	—	42	60	ns	

 Note: 6. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

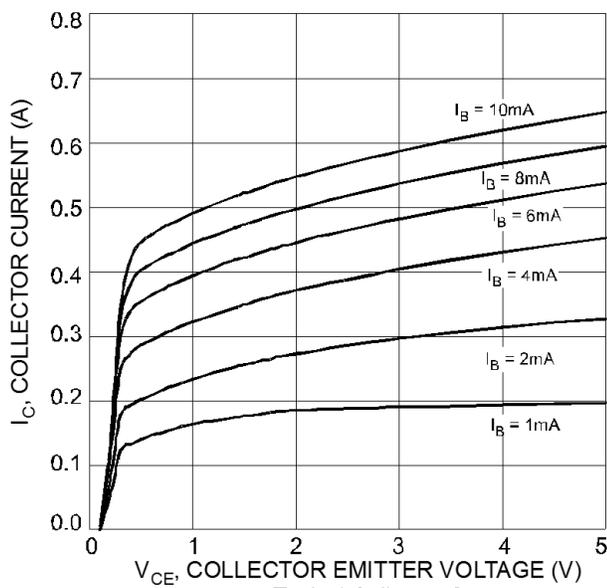


Figure 5. Typical Collector Current vs. Collector Emitter Voltage

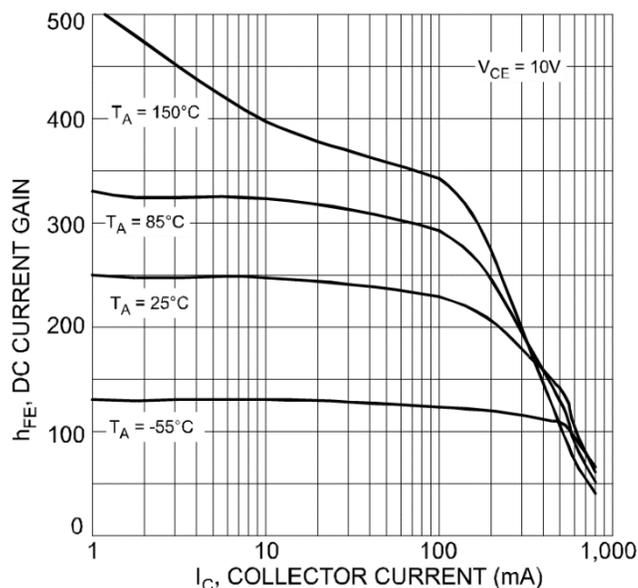


Figure 6. Typical DC Current Gain vs. Collector Current

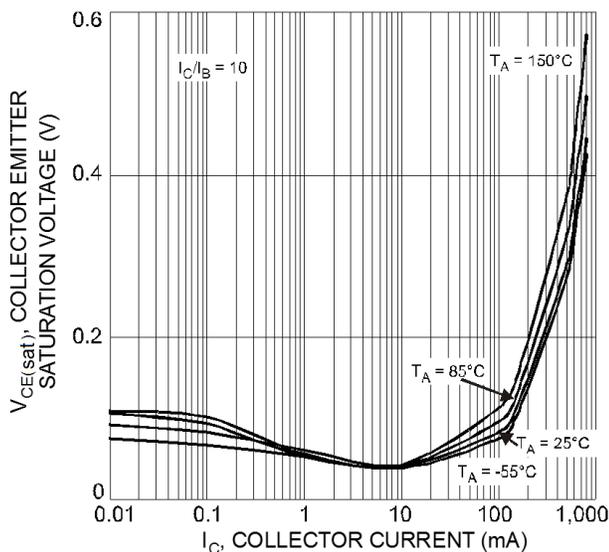


Figure 7. Typical Collector Emitter Saturation Voltage vs. Collector Current

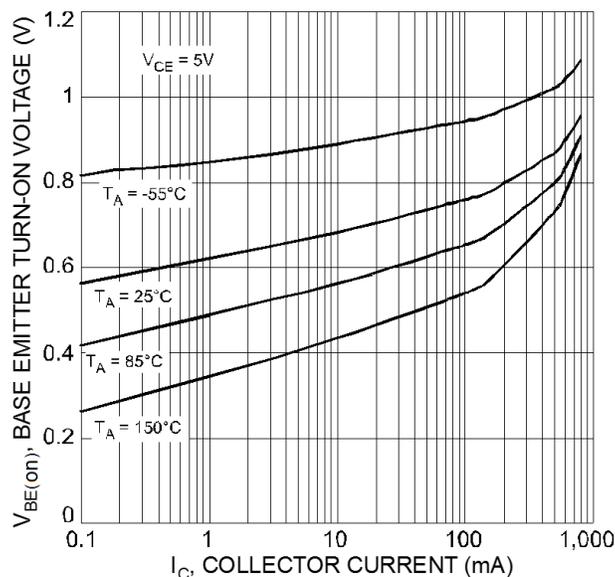


Figure 8. Typical Base Emitter Turn-On Voltage vs. Collector Current

Typical Electrical Characteristics (continued)

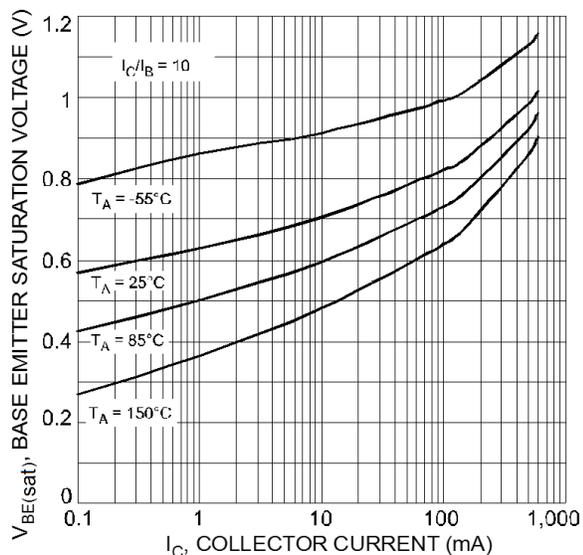


Figure 9. Typical Base Emitter Saturation Voltage vs. Collector Current

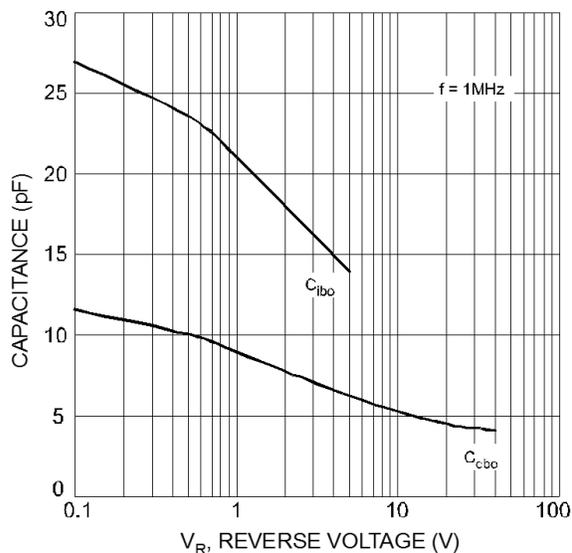


Figure 10. Typical Capacitance Characteristics

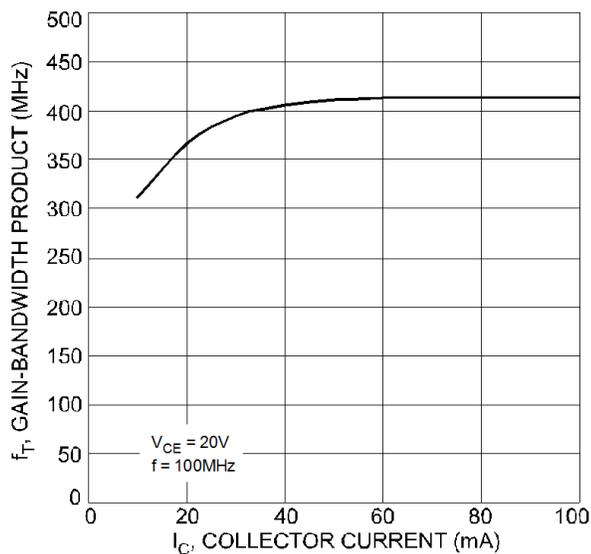
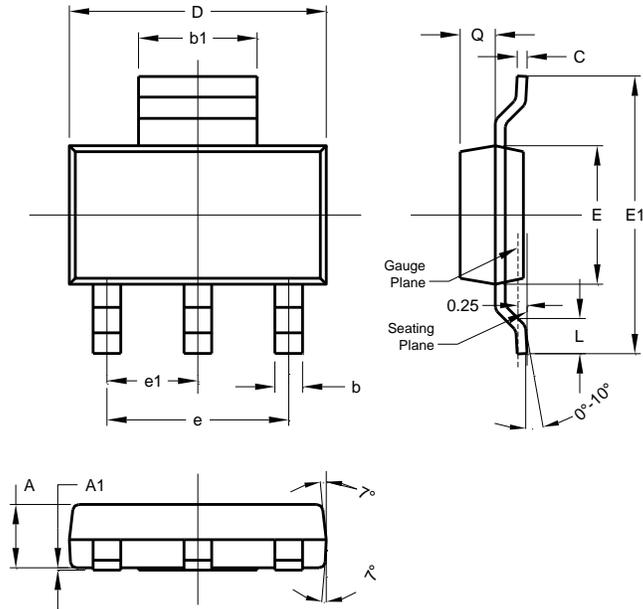


Figure 11. Typical Gain-Bandwidth Product vs. Collector Current

Package Outline Dimensions

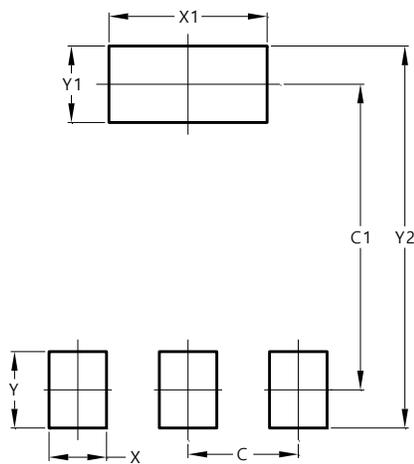
SOT223



SOT223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b	0.60	0.80	0.70
b1	2.90	3.10	3.00
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	-	-	4.60
e1	-	-	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89
All Dimensions in mm			

Suggested Pad Layout

SOT223



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00